

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently amended) ~~A circuit board~~ An apparatus comprising:  
  
    ~~a substrate;~~  
  
    a circuit board including a substrate and a set of electrical traces;  
  
    a plurality of through holes in the substrate; and  
  
    a malleable, electrically conductive material filled within each of the through holes.
2. (Currently amended) ~~A circuit board~~ An apparatus as recited in claim 1, ~~wherein the material is to receive an electrical contact of~~ further comprising an electronic component ~~when the electronic component is directly coupled to the circuit board, the electronic component having a plurality of electrical contacts, each in physical contact with the electrically conductive material in a separate one of the through holes.~~
3. (Currently amended) ~~A circuit board~~ An apparatus as recited in claim 2, wherein each ~~of said plurality of electrical contact~~ contacts is a pin.
4. (Currently amended) ~~A circuit board~~ An apparatus as recited in claim 2, wherein each ~~of said plurality of electrical contact~~ contacts is a solder ball.
5. (Currently amended) ~~A circuit board~~ An apparatus as recited in claim 1, wherein the electrically conductive material is an elastomer.
6. (Currently amended) ~~A circuit board~~ An apparatus as recited in claim 1, wherein the

through holes are tapered.

7. (Currently amended) A circuit board comprising:

a substrate having a first surface and a second surface parallel to the first surface; and

a set of electrical traces;

a plurality of tapered through holes in the substrate from the first surface to the second surface;

each of the through holes filled with an electrically conductive elastomer to receive a separate one of a plurality of electrical contacts of an electronic component, to couple the electronic component to the circuit board.

8. (Original) A circuit board as recited in claim 7, wherein the electrical contacts are pins that are inserted into the elastomer when the electronic component is coupled to the circuit board.

9. (Original) A circuit board as recited in claim 7, wherein the electrical contacts are solder balls that compress the elastomer when the electronic component is coupled to the circuit board.

10. (Original) A circuit board as recited in claim 7, wherein the elastomer includes conductive particles interspersed therein.

11. (Currently amended) An apparatus comprising:

a circuit board including

a substrate having a first surface and a second surface parallel to the first surface,

a set of electrical traces parallel to the first surface and the second surface,

a plurality of tapered through holes in the substrate from the first surface to the second surface, and

an electrically conductive elastomer filling each of the through holes, at least one of the electrical traces being in electrical contact with the electrically conductive elastomer in at least one of the through holes; and

an electronic component coupled to the circuit board, the electronic component having a plurality of electrical contacts, each in physical and electrical contact with the elastomer in a separate one of the through holes.

12. (Original) An apparatus as recited in claim 11, wherein the electrical contacts are pins, each inserted into the elastomer in a separate one of the through holes.

13. (Original) An apparatus as recited in claim 11, wherein the electrical contacts are solder balls, each of the solder balls compressing the elastomer in a separate one of the through holes.

14. (Original) An apparatus as recited in claim 13, further comprising a fastener to secure the electronic component to the circuit board.

15. (Original) An apparatus as recited in claim 11, wherein the elastomer includes conductive particles interspersed therein.

Claims 16-25. (Canceled).

26. (New) An apparatus as recited in claim 1, wherein at least one of the electrical traces is in electrical contact with the electrically conductive material in at least one of the through holes.

27. (New) An apparatus as recited in claim 1, wherein the circuit board includes an internal trace within the substrate, wherein the internal trace is in electrical contact with the electrically conductive material in at least one of the through holes at a location within the substrate.

28. (New) An apparatus as recited in claim 27, wherein each of said at least one of the through holes is defined by a separate surface of the substrate, wherein a conductive layer is disposed on said surface in each of said at least one of the through holes, and wherein the internal trace is in electrical contact with the conductive layer in each of said at least one of the through holes.

29. (New) A circuit board as recited in claim 7, wherein at least one of the electrical traces is in electrical contact with the electrically conductive elastomer in at least one of the through holes.

30. (New) A circuit board as recited in claim 29, including an internal trace within the substrate, wherein the internal trace is in electrical contact with the electrically conductive elastomer in at least one of the through holes at a location within the substrate.

31. (New) An apparatus as recited in claim 30, wherein each of said at least one of the through holes is defined by a separate surface of the substrate, wherein a conductive layer is disposed on said surface in each of said at least one of the through holes, and wherein the internal trace is in electrical contact with the conductive layer in each of said at least one of the through holes.

32. (New) An apparatus as recited in claim 11, wherein the circuit board includes an internal trace within the substrate, wherein the internal trace is in electrical contact with the electrically conductive elastomer in at least one of the through holes at a location within the substrate.

33. (New) An apparatus as recited in claim 32, wherein each of said at least one of the through holes is defined by a separate surface of the substrate, wherein a conductive layer is disposed on said surface in each of said at least one of the through holes, and wherein the internal trace is in electrical contact with the conductive layer in each of said at least one of the through holes.

34. (New) An apparatus as recited in claim 11, wherein the electronic component is coupled directly to the circuit board.